

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Die	Metal oxide	Lead Dioxide (PbO2)	1309-60-0	0.00177	0.92	0.1058
	Doped silicon	Silicon (Si)	7440-21-3	0.19042	99.08	11.3942
Subtotal				0.19219	100	11.5
Post-plating	Lead alloy	Tin (Sn)	7440-31-5	0.45458	100.0	27.2
Subtotal				0.45458	100	27.2
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.02006	0.03	1.20057
	Copper alloy	Iron (Fe)	7439-89-6	0.06688	0.1	4.0019
	Copper alloy	Copper (Cu)	7440-50-8	66.79431	99.87	3,996.69753
Subtotal				66.88125	100	NaN
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	2.09505	6.5	125.359
	Polymer	Epichlorohydrin/o-Cresol/Formaldehyde polymer (generic)	29690-82-2	5.15704	16.0	308.576
	Filler	Silica fused	60676-86-0	22.88436	71.0	1,369.306
	Flame retardant	Metal hydroxide		2.09505	6.5	125.359
Subtotal				32.2315	100	NaN
Solder Wire	Lead alloy	Tin (Sn)	7440-31-5	0.0045	5.0	0.2695
	Lead alloy	Silver (Ag)	7440-22-4	0.00225	2.5	0.13475
	Lead alloy	Lead (Pb)	7439-92-1	0.08332	92.5	4.98575
Subtotal				0.09007	100	5.39
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.15041	100.0	9
Subtotal				0.15041	100	9
Total				100	100	NaN

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